

**Integrated chip package structure using metal substrate and method of
manufacturing the same**

Appl. No. : 10/055,560 Confirmation No. 6103
Applicant : Mou-Shiung Lin,
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Examiner : Mitchell, James M
Docket No. : MEGP0009USA
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT

5 Sir:

In response to the Office Action mailed May 21, 2007, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 8 of this paper.